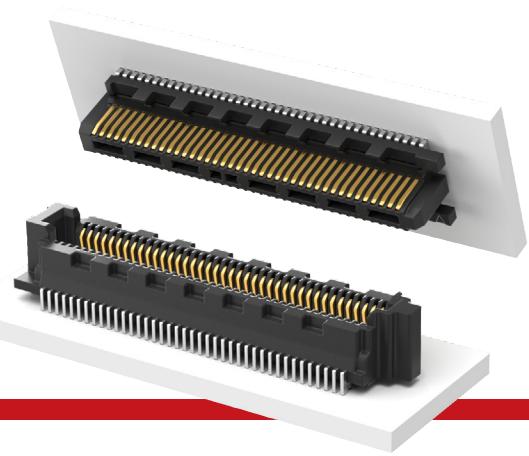


# MICRO BLADE & BEAM SOCKET & HEADER

28  
Gbps

(0.40 mm) .0158" PITCH • SS4/ST4 SERIES



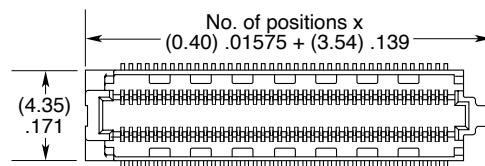
**SS4**  
Mates:  
ST4

**ST4**  
Mates:  
SS4

<b>SS4</b>	<b>POSITIONS PER ROW</b>	<b>LEAD STYLE</b>	<b>PLATING OPTION</b>	<b>D</b>	<b>K</b>	<b>"X"R</b>
	<b>-10, -20, -30, -40, -50</b>	<b>-3.00</b> = 3.00 mm	<b>-L</b> = 10 $\mu$ " (0.25 $\mu$ m) Gold on contact, Matte Tin on tail		(Required in callout)	
		<b>-3.50</b> = 3.50 mm	<b>-K</b> = (3.50 mm) .138" DIA Polyimide Film Pick & Place Pad		(Required in callout)	

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50  $\mu$ " (1.27  $\mu$ m) Ni  
**Operating Temp Range:** -55 °C to +125 °C  
**Current Rating:** 1.6 A per pin (2 pins powered)  
**Voltage Rating:** 155 VAC/219 VDC

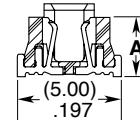
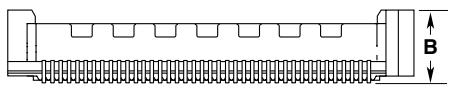
## SPECIFICATIONS



LEAD STYLE	A	B
-3.00	(2.85) .112	(3.50) .138
-3.50	(3.35) .132	(4.00) .157

## PROCESSING

**Lead-Free Solderable:** Yes  
**SMT Lead Coplanarity:** (0.10 mm) .004" max



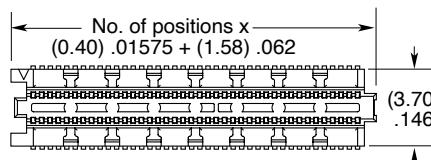
## MATED HEIGHT \*

ST4 LEAD STYLE	SS4 LEAD STYLE	
-3.00	-3.00	-3.50
-1.00	(4.00 mm) .157"	(4.50 mm) .177"
-1.50	(4.50 mm) .177"	(5.00 mm) .197"
-2.50	(5.50 mm) .217"	(6.00 mm) .236"

\*Processing conditions will affect mated height.

<b>ST4</b>	<b>POSITIONS PER ROW</b>	<b>LEAD STYLE</b>	<b>PLATING OPTION</b>	<b>D</b>	<b>P</b>	<b>"X"R</b>
	<b>-10, -20, -30, -40, -50</b>	<b>-1.00</b> = 1.00 mm	<b>-L</b> = 10 $\mu$ " (0.25 $\mu$ m) Gold on contact, Matte Tin on tail		(Required in callout)	

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50  $\mu$ " (1.27  $\mu$ m) Ni  
**Operating Temp Range:** -55 °C to +125 °C  
**Current Rating:** 1.6 A per pin (2 pins powered)  
**Voltage Rating:** 155 VAC/219 VDC



LEAD STYLE	A	B
-1.00	(1.00) .039	(3.08) .121
-1.50	(1.50) .059	(3.58) .141
-2.50	(2.50) .098	(4.58) .180

## Note:

Some lengths, styles and options are non-standard, non-returnable.